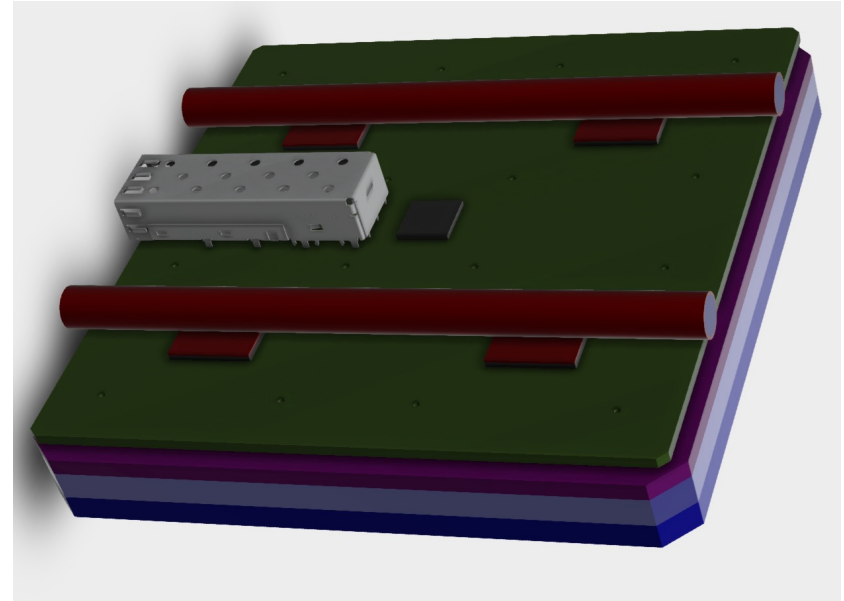
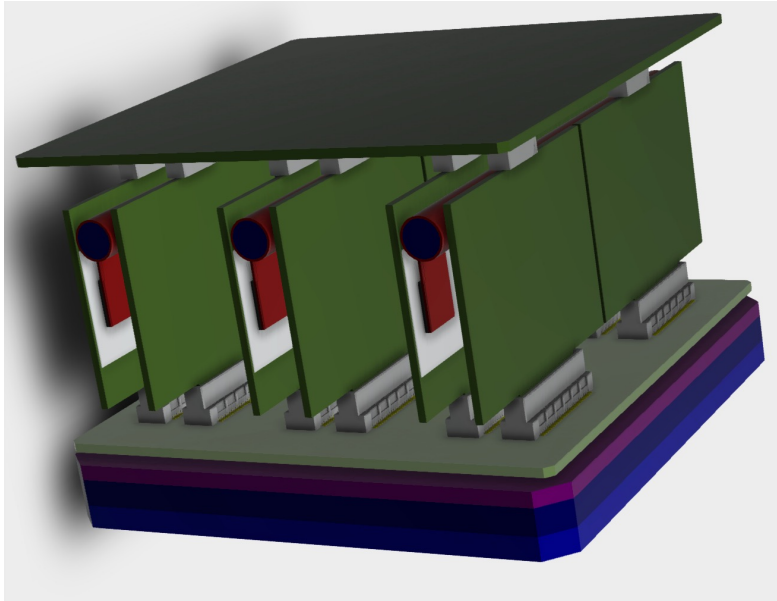


Update on front end electronics

- Consider departing from WFD ASICs and switching to ToA/ToT(ADC) ones
- EICROC: a solution for AC-LGAD ToF layers, supported by the EIC project
 - Will have a joint meeting with the experts next week (?)



Update on HRPPD-to-ASIC interface

- Have a pretty clear idea how to interface EICROC-like electronics
 - Use Samtec high density compression interposers

COMPRESSION HARDWARE

ULTRA LOW PROFILE SYSTEMS FOR Z-RAY® INTERPOSERS

- Designed for Z-Ray®, the lowest profile, most flexible high-density micro interposer in the industry (ZA8 and ZA1 Series)
- Precise alignment, compression and retention of interposers with either dual compression (LGA) or single compression with solder balls (BGA)
- Ultra low profile
- Reduces risk of damage to the interposer
- ZSO Series for single compression with solder balls
- ZHSI and ZD Series for dual compression interposers

Protects solder ball joints when compressed

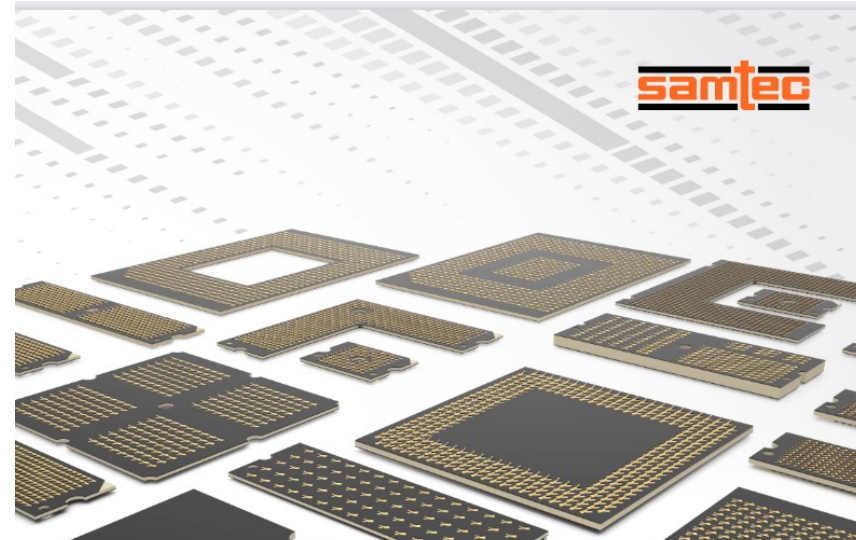
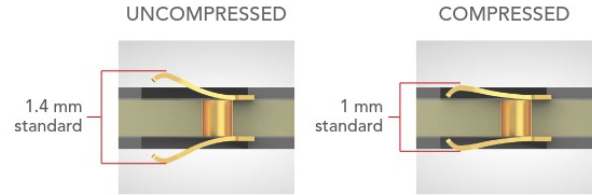
ZSO

ZD

ZHSI

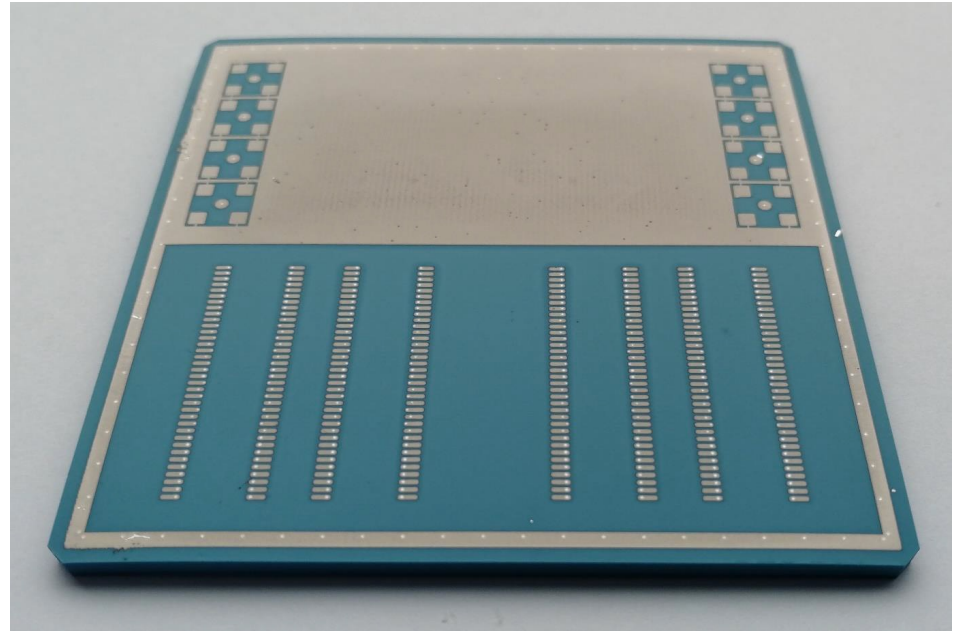
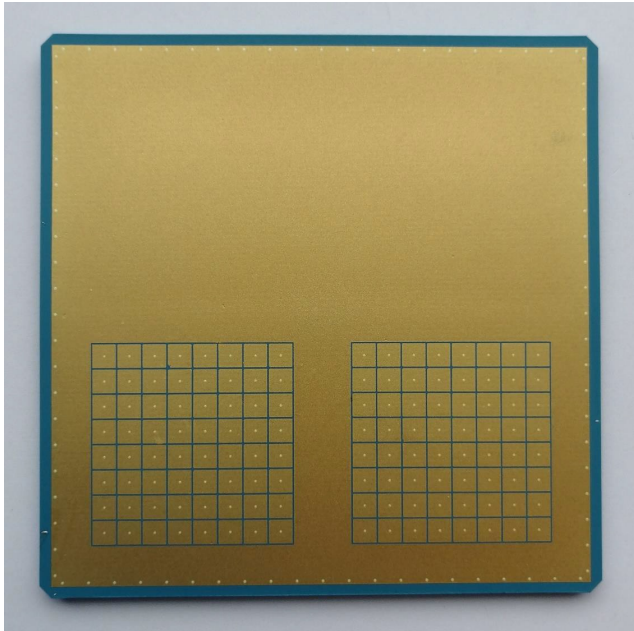
Provides alignment and compression

Provides alignment



Update on HRPPD packaging

- Techtra produced a second (thinner) 3" HRPPD anode base plate prototype
 - Flatness is a bit of an issue, but plating became better
 - Will see both parts in ~two weeks



Update on GEANT environment

- A very detailed geometry and material description (up to the services block)
 - Shorter electronics section (a la EICROC)
 - Longer expansion volume
 - Beam pipe cutaway matching CAD model
- MARCO magnetic field
- HepMC3 input (yet with limitations)
- HRPPD pixellation (spatial resolution)

